

ABSTRACT OF THE DISCLOSURE

An improved device for cleaning probe pins of a probe head assembly is presented. The device includes a first holding plate, a second holding plate and a cleaning cartridge. The first holding plate secures the probe head assembly. The second holding plate secures the cleaning cartridge in proximity to the first holding plate. The cleaning cartridge has a chamber. The chamber includes a cleaning solution and an absorbent pad located therein. The absorbent pad is saturated with the cleaning solution and prevents leakage of the cleaning solution out of the chamber. During cleaning operations, the first holding plate is positioned about the second holding plate such that the probe pins of a probe head extend into and contact the absorbent pad in the chamber. Once contact is established, the cleaning solution acts upon the probe pin tips to remove unwanted debris. A depth of penetration of the pins into the pad is controlled by a surface of the cartridge.